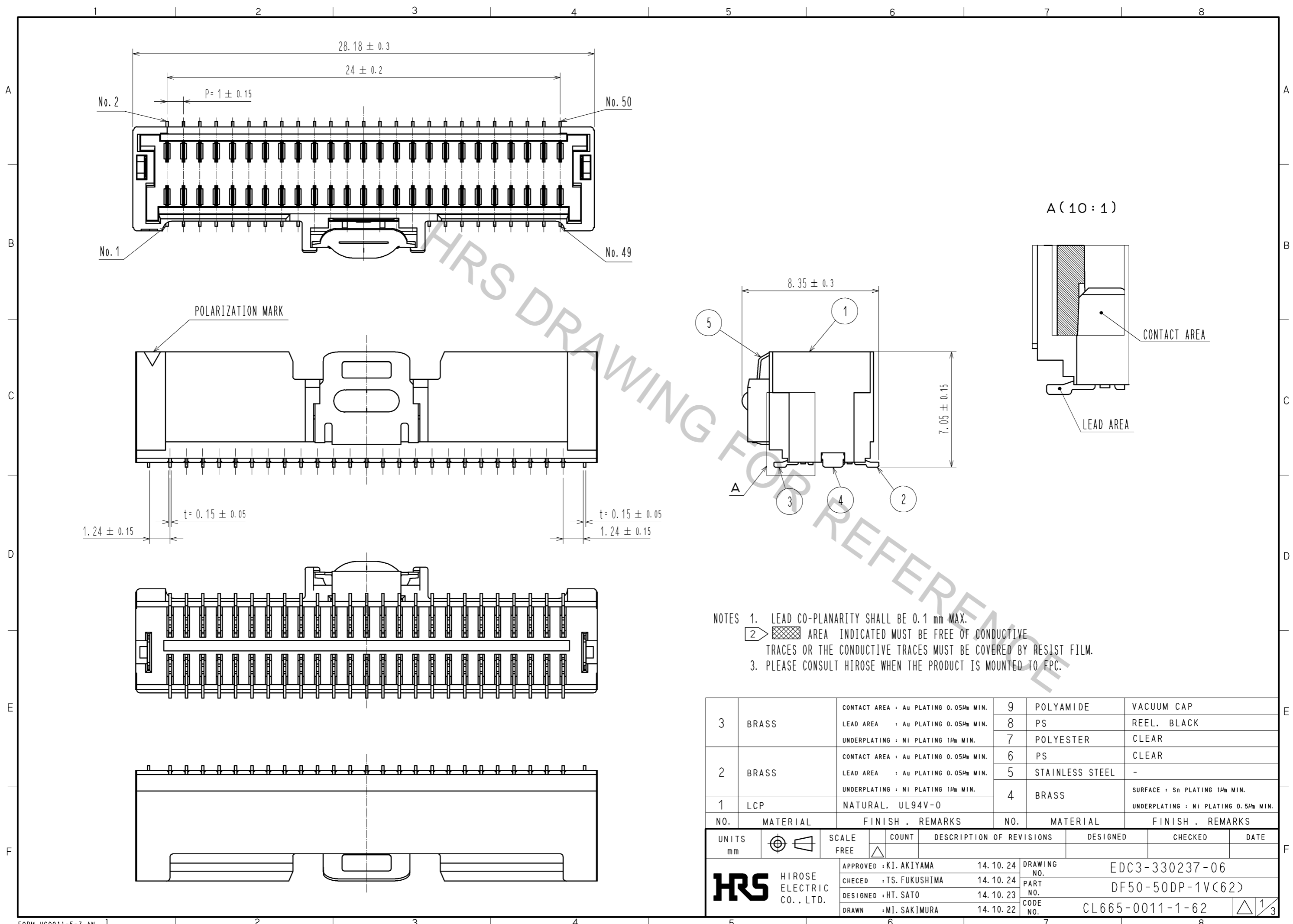


Apr.1.2017 Copyright 2017 HIROSE ELECTRIC CO., LTD. All Rights Reserved.



NOTES

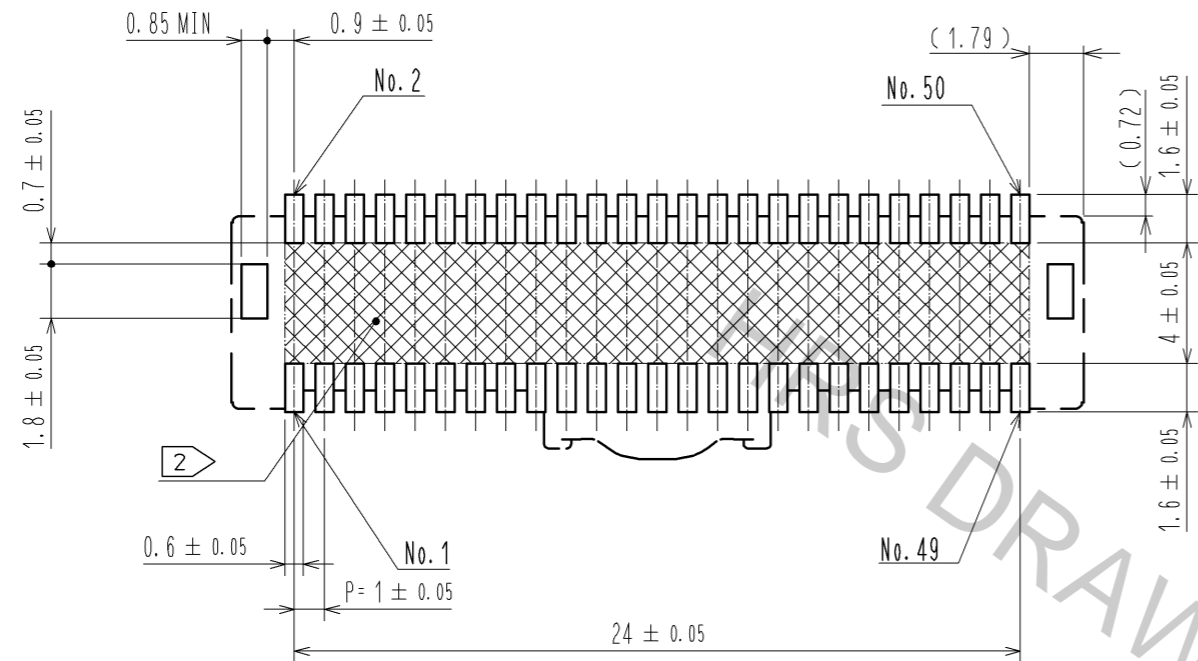
1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO EPC.

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN. LEAD AREA : Au PLATING 0.05μm MIN. UNDERPLATING : Ni PLATING 1μm MIN.	9	POLYAMIDE	VACUUM CAP
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN. LEAD AREA : Au PLATING 0.05μm MIN. UNDERPLATING : Ni PLATING 1μm MIN.	8	PS	REEL, BLACK
1	LCP	NATURAL, UL94V-0	7	POLYESTER	CLEAR
			6	PS	CLEAR
			5	STAINLESS STEEL	-
			4	BRASS	SURFACE : Sn PLATING 1μm MIN. UNDERPLATING : Ni PLATING 0.5μm MIN.

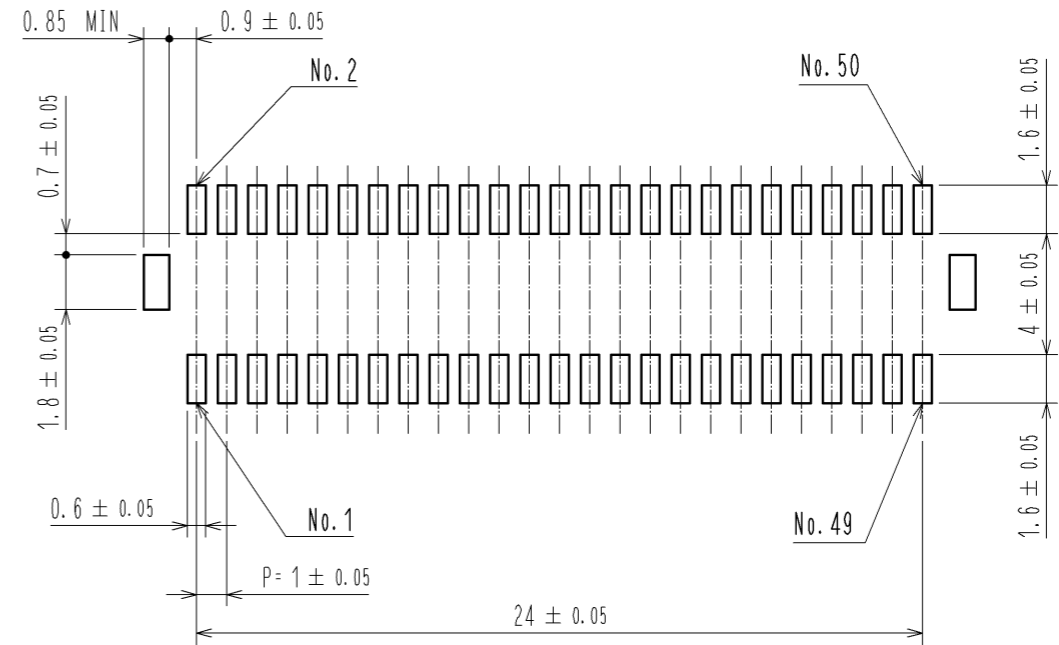
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	FREE	△				
APPROVED : KI. AKIYAMA			14.10.24	DRAWING NO. EDC3-330237-06		
CHECED : TS. FUKUSHIMA			14.10.24	PART NO. DF50-50DP-1V(62)		
DESIGNED : HT. SATO			14.10.23	CODE NO. CL665-0011-1-62		
DRAWN : MI. SAKIMURA			14.10.22	△ 1/3		

Apr.1.2017 Copyright 2017 HIROSE ELECTRIC CO., LTD. All Rights Reserved.

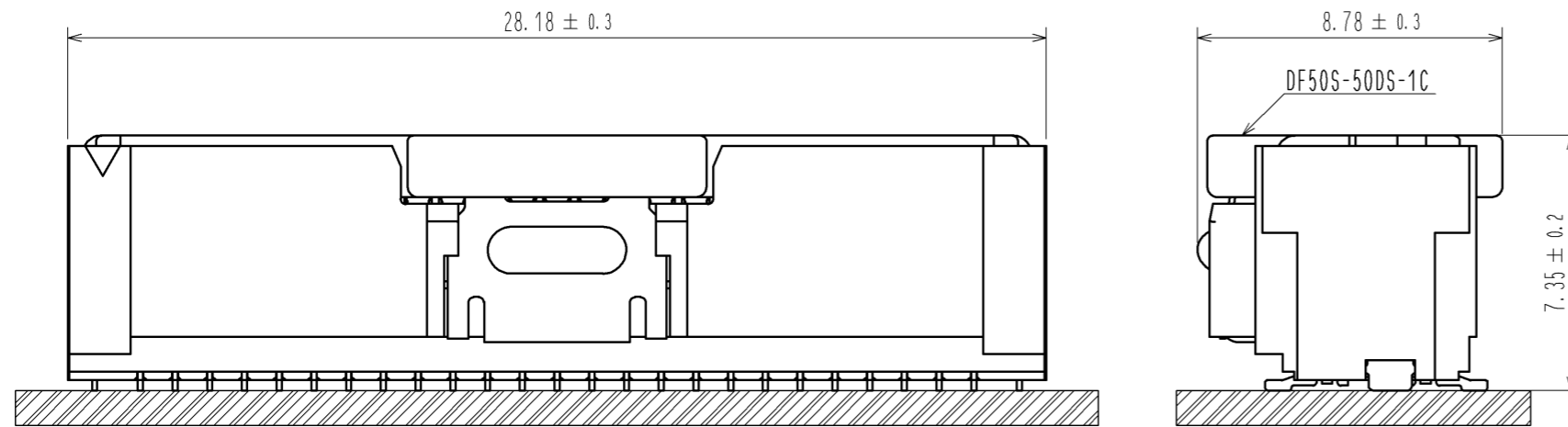
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



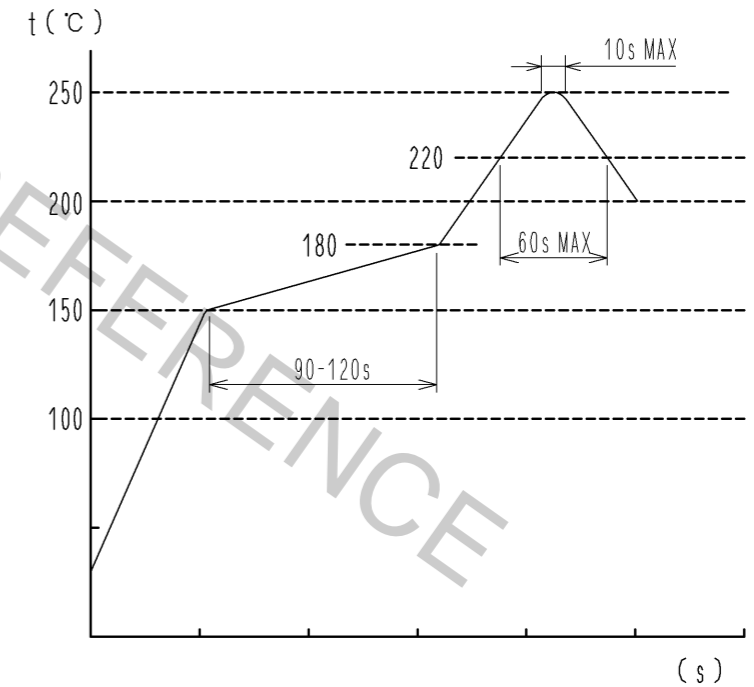
RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm



MATING FIGURE (5 : 1)



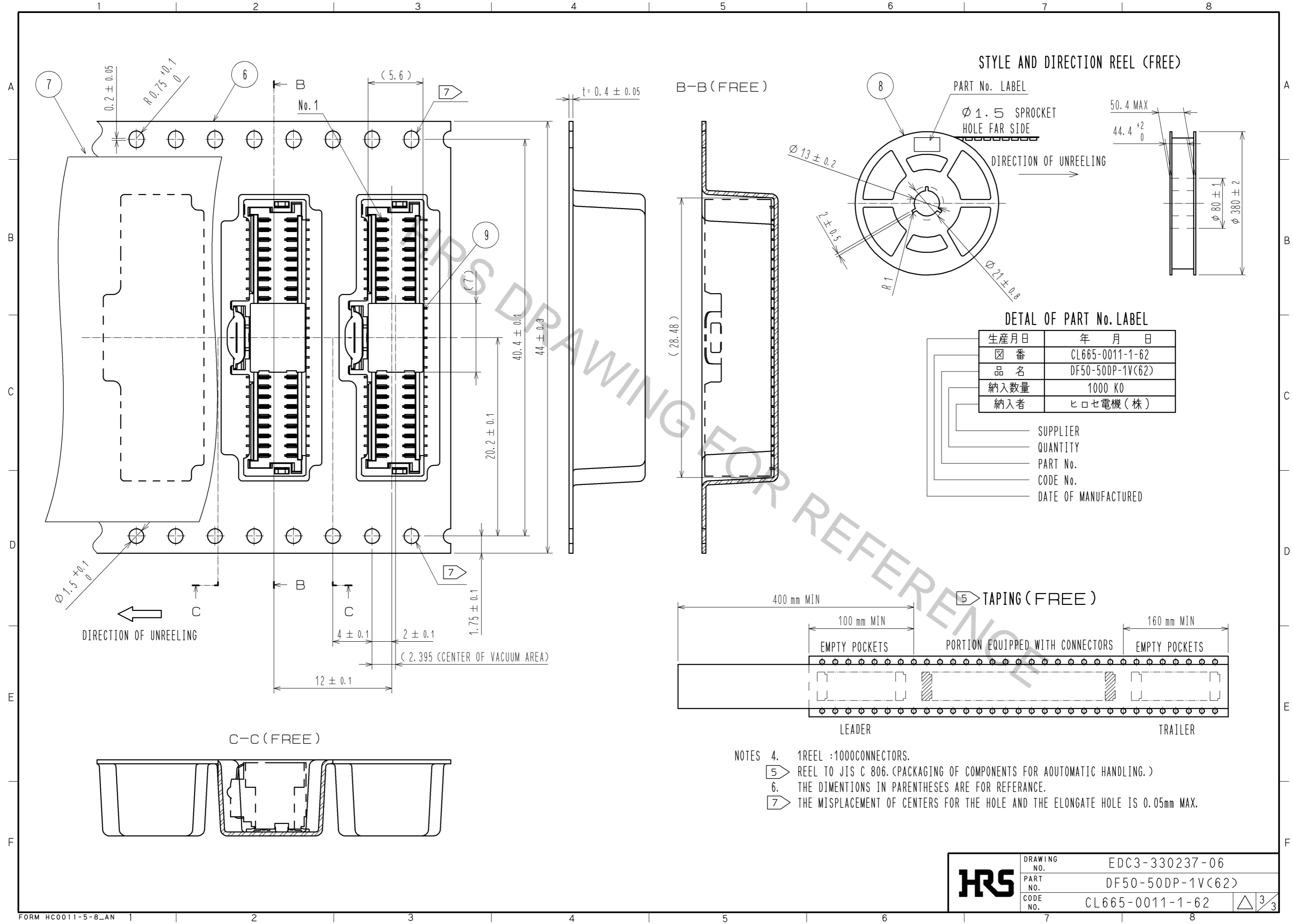
REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE(REFERENCE)



NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MEASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
METAL etc.

HRS	DRAWING NO.	EDC3-330237-06
	PART NO.	DF50-50DP-1V(62)
	CODE NO.	CL665-0011-1-62
		△ 2/3



HRS	DRAWING NO.	EDC3-330237-06
	PART NO.	DF50-50DP-1V(62)
	CODE NO.	CL665-0011-1-62
		△ 3/3